

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Takashi Kumamoto et al.
Serial No. : 09/878,123
Filed : June 8, 2001
Title : CHIP LEAD FRAMES

Art Unit : Unknown
Examiner : Unknown

Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Prior to examination, please amend the application as follows:

In the specification:

Replace the paragraph beginning at page one, line six with the following rewritten paragraph:

This application claims priority under 35 U.S.C. as a continuation-in-part of U.S. Patent Application Serial No. 09/741,535, filed on December 19, 2000, the entire contents of which are hereby incorporated by reference.

In the claims:

Amend claims 1, 6, 10, and 13 as follows:

- A1
1. A device comprising:
 - a lead frame having conductive leads and an insulative composition interposed between the leads;
 - a die having a lower die surface that is connected by contacts to the lead frame, and is spaced by a gap from a first region of the lead frame; and

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I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

8-1-01
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Signature

Marie A. Colakathis
Typed or Printed Name of Person Signing Certificate

A1
a polymer composition that forms a continuous network that forms a layer that extends at least above the lower die surface and covers regions of the lead frame surface that are outside the first region and are not occupied by any component.

A2
6. A device comprising:
a conductive substrate;
a die having a lower die surface that is connected by contacts to the substrate, and is spaced by a gap from the substrate; and
a polymer composition that forms a network on a region of the substrate that extends at least above the lower die surface, the layer imparting sufficient rigidity to the device to maintain integrity of the contacts during etching of the substrate in the absence of a supporting frame.

A3
10. A device comprising:
a lead frame;
a die having a lower die surface that is connected by contacts to, and is spaced by a gap from a first region of the lead frame;
a peripheral component also connected to the lead frame at a location other than in the first region; and
a polymer composition that extends in a direction normal to the lead frame at least above the lower die surface and extends along a surface of the lead frame from the die to the peripheral component.

A4
13. A method comprising:
a) causing a compound to enter a gap between a substrate and a die connected to the substrate and to form a layer on an upper surface of the substrate; and
b) setting the compound to generate a continuous, rigid network that extends within the gap and forms a layer surrounding the die perimeter.

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In the Drawings:

Please replace Figures 1A, 1B, and 2AB with the enclosed substitute figures.

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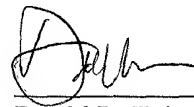
Attorney's Docket No.: 10559-445001 / P10668

REMARKS

Applicant asks that all claims be examined. Please apply any charges or credits to Deposit Account No. 06-1050, referencing attorney docket number 10559-445001.

Respectfully submitted,

Date: 8/1/01



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